

200V N-Channel MOSFETs

Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- Improved dv/dt capability
- · Fast switching
- Green Device Available
- RoHS compliant package

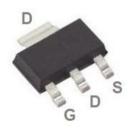
Applications

- · High efficient switched mode power supplies
- TV Power
- Adapter/charger
- LED Lighting
- · Networking

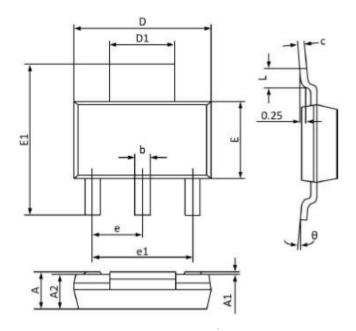
Package type: SOT-223

Packing & Order Information

3,000/Reel

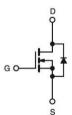






Symbol	Dimensions In	Millimeters	Dimensions	In Inches
	MAX	MIN	MAX	MIN
A	1.800	1.520	0.071	0.060
Al	0.100	0.000	0.004	0.000
A2	1.700	1.500	0.067	0.059
b	0.820	0.660	0.032	0.026
c	0.350	0.250	0.014	0.010
D	6.400	6.200	0.252	0.244
D1	3.100	2.900	0.122	0.114
E	3.700	3.300	0.146	0.130
El	7.070	6.830	0.278	0.269
e	2.30(BSC)	0.091(BSC)	
el	4.700	4.500	0.185	0.177
L	1.150	0.900	0.045	0.035
θ	10°	0°	10°	0°

Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (T _A =25°C unless otherwise noted)						
Symbol	Parameter	Value	Unit			
V_{DS}	Drain-Source Voltage	200	V			
V_{GS}	Gate-Source Voltage	±30	V			
T_	Drain Current - Continuous (Tc=25°C) (Chip Limitation)	3	A			
\mathbf{I}_{D}	Drain Current - Continuous (T _C =100°C) (Chip Limitation)	1.9	A			
I_{DM}	Drain Current - Pulsed ¹	12	A			
P_D	Power Dissipation (T _C =25°C)	1.78	W			



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Absolute Maximum Ratings (T _A =25°C unless otherwise noted)						
Symbol	Parameter	Value	Unit			
$T_{\rm J}$	Operating Junction Temperature Range	-55 to +150	°C			
T _{STG}	Storage Temperature Range	-55 to +150	°C			

Thermal Characteristics						
Symbol	Parameter	Typ.	Max.	Units		
$R_{\Theta jA}$	Thermal Resistance Junction to ambient		70	°C AV		
$R_{\theta JC}$	Thermal Resistance Junction to Case		20	°C/W		

Electrical Characteristics (TJ=25°C, unless otherwise noted)

Off Characteristics							
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units	
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = V_{GS}, I_D = 250uA$	200			V	
ΔBV_{DSS} / ΔTJ	BVDSS Temperature Coefficient	Reference to 25°C, ID=1mA		0.5		V/°C	
I_{GSS}	Gate-Source Leakage Current	$V_{DS} = 0 V$, $V_{GS} = \pm 30 V$			±100	nA	
I_{DSS}	Drain-Source Leakage Current	$\begin{aligned} V_{DS} &= 200 \ V \ , \ V_{GS} &= 0 \ V \ , \ T_J = 25 ^{\circ} C \\ V_{DS} &= 160 \ V \ , \ V_{GS} &= 0 \ V \ , \ T_J = 125 ^{\circ} C \end{aligned}$			1 10	uA	

On Characteristics							
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units	
$R_{DS \left(on\right)}$	Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_{D} = 2 \text{ A}$		0.7	0.85	mΩ	
$V_{GS(th)} \\$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	3	4	5	V	
$\Delta V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{\rm DS} = V_{\rm GS}, I_{\rm D} \! = \! \! -250 \mu A$		-8		mV/°C	
g _{fs}	Forward Tranconductance	$V_{DS} = 10 \text{ V}, I_{D} = 2 \text{ A}$		3.6		S	

Dynamic	Dynamic and switching Characteristics							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units		
$t_{d(on)} \\$	Turn-On Delay Time ^{3,4}	$I_{D} = 1 \text{ A}, R_{G} = 25 \Omega,$ $V_{GS} = 10 \text{ V}, V_{DD} = 100 \text{ V}$		10	20	ns		
$t_{\rm r}$	Rise Time ^{3,4}			35	70	ns		
$t_{ m d(off)}$	Turn-Off Delay Time ^{3,4}			10	20	ns		
tf	Fall Time ^{3,4}			28	56	ns		
Ciss	Input Capacitance			266	500	pF		
Coss	Output Capacitance	$\begin{split} V_{DS} &= 25 \ V \\ f &= 1 \ MHz \ , \ V_{GS} = 0 \ V \end{split} \label{eq:VDS}$		160	300	pF		
Crss	Reverse Transfer Capacitance			55	110	pF		
Rg	Total Gate Charge	$V_{DS} = 0 \ V$, $f = 1 \ MHz$, $V_{GS} = 0 \ V$		1.5	3	Ω		



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Dynamic and switching Characteristics								
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units		
Q_g	Total Gate Charge ^{3,4}	$V_{DS} = 160 \text{ V}, I_{D} = 1 \text{ A},$ $V_{GS} = 10 \text{ V}$		4.8	9	nC		
$Q_{\rm gs}$	Gate-Source Charge ^{3,4}			2	4	nC		
Q_{gd}	Gate-Drain Charge 3,4	VGS - 10 V		0.8	2	nC		

Drain-Source Diode Characteristics and Maximum Ratings							
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units	
Is	Continuous Source Current	$V_G = V_D = 0 \text{ V}$, Force Current			1	A	
I_{SM}	Pulsed Source Current				2	A	
V _{SD}	Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.3 \text{ A}, TJ = 25 ^{\circ}\text{C}$			1	V	
trr	Reverse Recovery Time	$V_{GS} = 0 V$, $I_S = 1 A$,				ns	
Qrr	Reverse Recovery Charge	di/dt=100A/µs , TJ=25°C				nC	

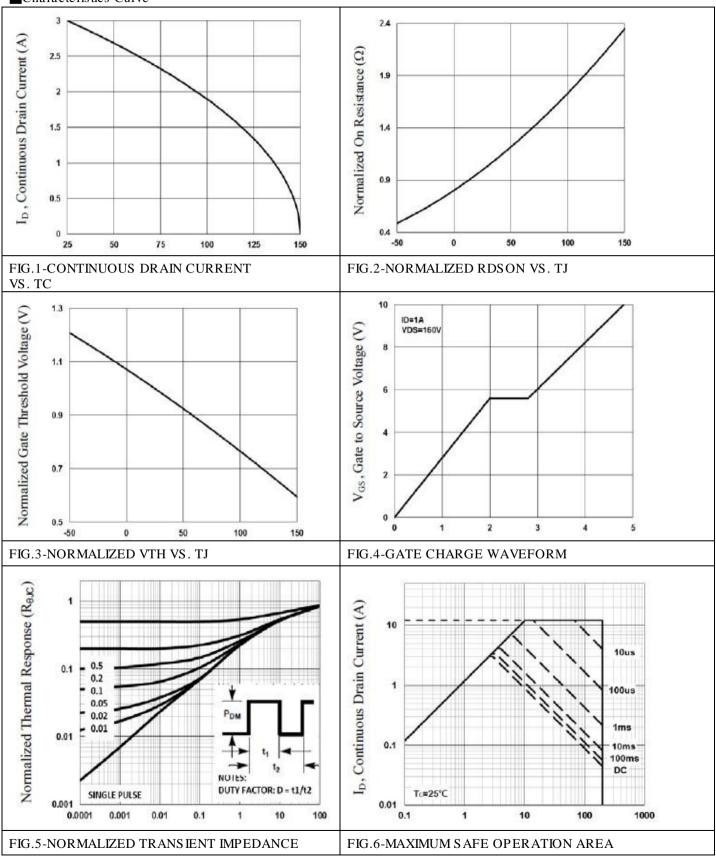
Note:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$.
- 3. Essentially independent of operating temperature.



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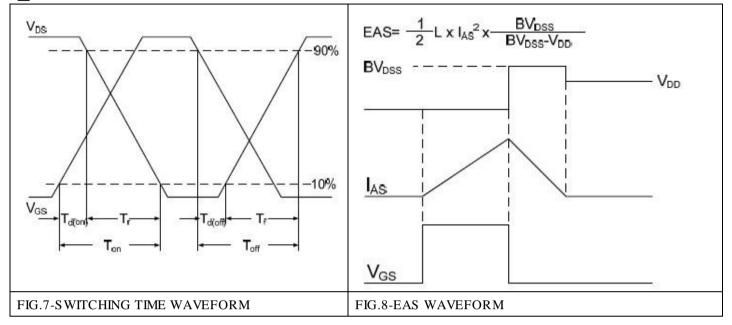
Characteristics Curve





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Characteristics Curve





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